

ABSTRACT

A semiconductor component includes a semiconductor die, 5 and an on board capacitor on the die for filtering transient voltages, spurious signals and power supply noise in signals transmitted to the die. The capacitor includes a first electrode in electrical communication with a first terminal contact for the component, and a second electrode in 10 electrical communication with a second terminal contact for the component. The electrodes are separated by a dielectric layer and protected by an outer protective layer of the component. The capacitor can be fabricated using redistribution layers on a wafer containing multiple dice. 15 The component can be used to construct systems such as multi chip packages and multi chip modules.

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